ASSOCIATION CONNECTINE ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ous Materia	ials and Mfg Information				
Supplier Inform	ation														
Company name*			Company unique ID			ī	Unique ID Authority					Response Date*			
nsemi												2025-06-04			
Contact Name		Title - Contact				Phone - Contact*					Email - Contact*				
Product-Env-Stewa	rds		Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com			
uthorized Represe	ntative*		Title - Representative			1	Phone - Representative*				Email - Representative*				
Product-Env-Stewa	rds	Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com				
Requeste	Requester Item Number Mfr Item		m Number Mfr Item Name				Effective Date Version Manufacturing S		ing Site	Weight*		UOM	Unit Type		
		NCV8705MWADJTC 500 mA Ultra		500 mA Ultra-Lo	ow Noise LDO, ADJ		2025-06-04	04 MY1			22.54 mg		mg	Each	
Ianufacturing	Proccess Information	n													
Terminal Plating / Grid Array Material Terminal I			erminal Base A	l Base Alloy J-STD-020 MSL			Peak Process Body Temperature Max Time at Peal				ne at Peak	Temperati	ıre Num	ber of Reflow Cy	cles
Matte Tin (Sn) - annealed		C	CU Alloy 1				260 C		С	30 seco		secono	is 3		
omments															
vel 1 - maximum ti	ime at peak temperature o	during solo	dering is 10-3	0 seconds											
or more informatio	on regarding material con	nposition p	olease refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and correct one bents it is form. Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.28	mg	Supplier	Silicon (Si)	7440-21-3		0.28	mg
Die Attach	0.07	mg	Supplier	Epoxized Condensate Of Para- Hydrobenzaldehyde And Alkyl Phenol	129915-35-1		0.014	mg
			Supplier	Silver (Ag)	7440-22-4		0.056	mg
Lead Frame	7.7		Supplier	Zinc (Zn)	7440-66-6		0.0077	mg
			Supplier	Iron (Fe)	7439-89-6		0.1771	mg
			Supplier	Copper (Cu)	7440-50-8		7.5075	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0077	mg
Mold Compound-Black	14.15			Epoxy resin	proprietary data		1.0612	mg
			Supplier	Phenolic Resin	Proprietary Data		0.3537	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		1.0612	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0707	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		11.603	mg
Plating	0.06	mg	Supplier	Tin (Sn)	7440-31-5		0.06	mg
Wire Bond - Au	0.28	mg	Supplier	Gold (Au)	7440-57-5		0.28	mg